

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0117I uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =100V,I_D =17A

 $R_{DS(ON)} < 70 \text{m}\Omega$ @ $V_{GS}=10V$ (Typ:56m Ω)

 $R_{DS(ON)} < 85m\Omega$ @ V_{GS} =4.5V (Typ:65m Ω)

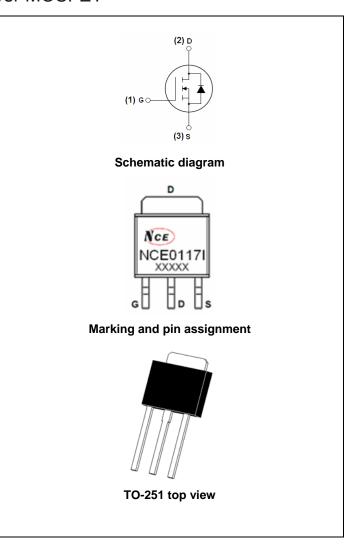
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits

100% UIS TESTED!

100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0117I	NCE0117I	TO-251	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	17	А
Drain Current-Continuous(T _C =100°C)	I _D (100°ℂ)	12	А
Pulsed Drain Current	I _{DM}	60	А
Maximum Power Dissipation	P _D	55	W
Single pulse avalanche energy (Note 5)	E _{AS}	28	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$



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Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	R _{eJC}	2.27	°C/W	Ī
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.8	2.5	V
Daile Communication Constitution	-	V _{GS} =10V, I _D =5A	-	56	70	mΩ
Drain-Source On-State Resistance	ard Transconductance g _{FS} mic Characteristics (Note4)	V _{GS} =4.5V, I _D =3A		65	85	
Forward Transconductance	g FS	V _{DS} =5V,I _D =5A	12	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss})/ 05)/)/ 01/	-	1350	-	PF
Output Capacitance	C _{oss}	V_{DS} =25V, V_{GS} =0V,	-	240	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	180	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$		-	13.8	-	nS
Turn-on Rise Time	t _r	V_{DD} =30 V , R_L =15 Ω	-	9.3	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =2.5 Ω	-	43.8	-	nS
Turn-Off Fall Time	t _f		-	11.4	-	nS
Total Gate Charge	Qg	\/ 00\/1 5A	-	30		nC
Gate-Source Charge	Q _{gs}	V_{DS} =30 V , I_{D} =5 A ,	-	6.4	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	8.6	-	nC
Drain-Source Diode Characteristics	ı					1
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =17A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	17	Α
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is neg	ligible (turi	n-on is do	ominated b	v LS+LD

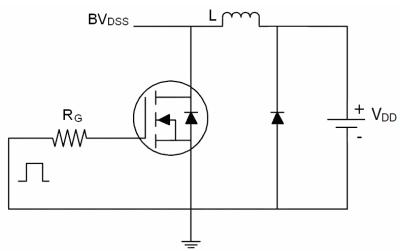
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω

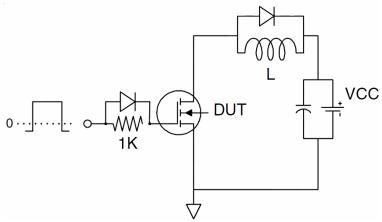


Test Circuit

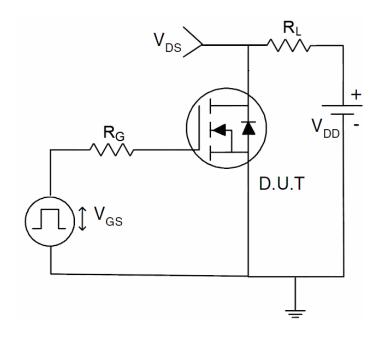
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







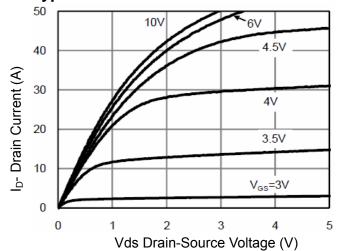


Figure 1 Output Characteristics

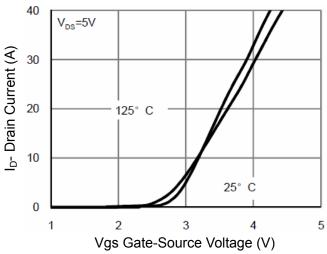


Figure 2 Transfer Characteristics

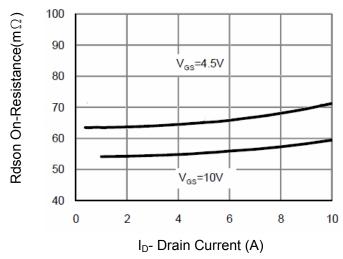


Figure 3 Rdson- Drain Current

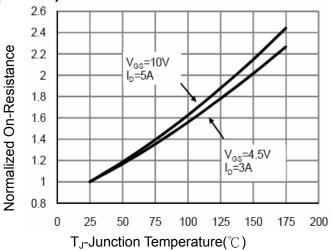


Figure 4 Rdson-JunctionTemperature

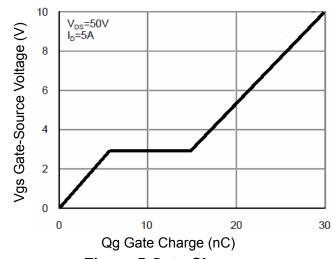


Figure 5 Gate Charge

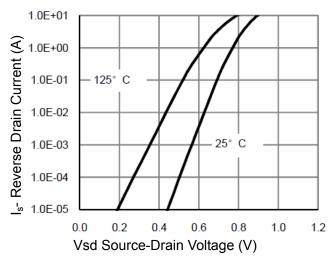


Figure 6 Source- Drain Diode Forward



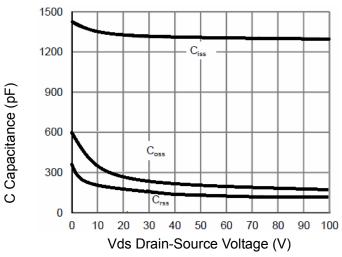


Figure 7 Capacitance vs Vds

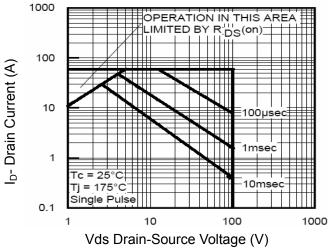


Figure 8 Safe Operation Area

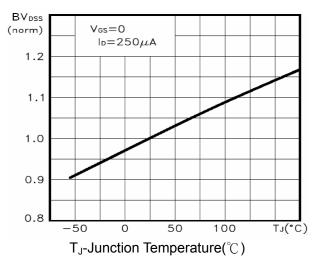


Figure 9 BV_{DSS} vs Junction Temperature

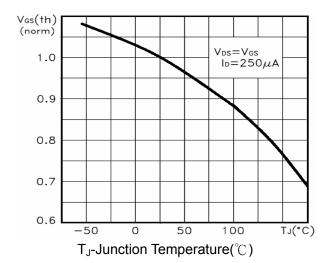


Figure 10 V_{GS(th)} vs Junction Temperature

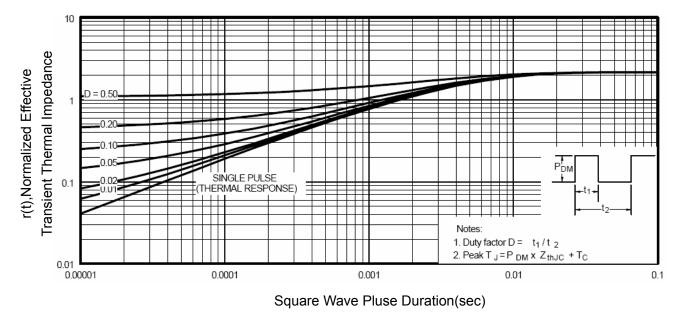
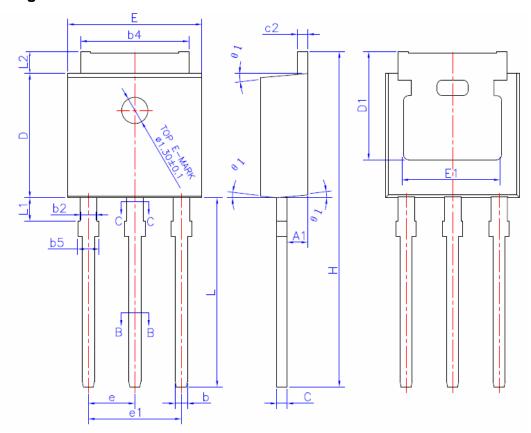
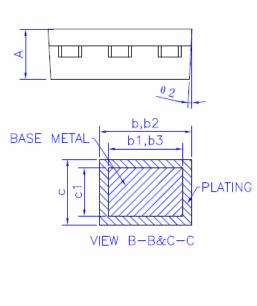


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-251 Package Information





COMMON DIMENSIONS (UNITS OF MEASURE =MILLIMETER)

SYMBOL	MIN	NOM	MAX
Α	2.20	2,30	2,35
A1	0,90	1,01	1,10
b	0.56		0.69
b1	0.55	0.60	0.65
b2	0.77		0.90
b3	0.76	0.81	0.86
b4	5,23	5,33	5,43
b5			1.05
С	0.46		0.59
c1	0.45	0.51	0.55
c2	0.46		0.59
D	6.00	6.10	6.20
D1	5.20		—
E	6.50	6.60	6.70
E1	4.60	4,83	5.00
е	2.24	2,29	2.34
e1	4.47	4.57	4.67
Н	16.18	16,48	16.78
L	9.00	9.30	9.60
L1	0.95	1,16	1,35
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°



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